

SOT102-4

plastic dual in-line package; 18 leads (300 mil); long body

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DIP18
Package type industry code	DIP18
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-001
Mounting method type	T (through-hole mount)
Issue date	12-3-2003

Table 1. Package summary

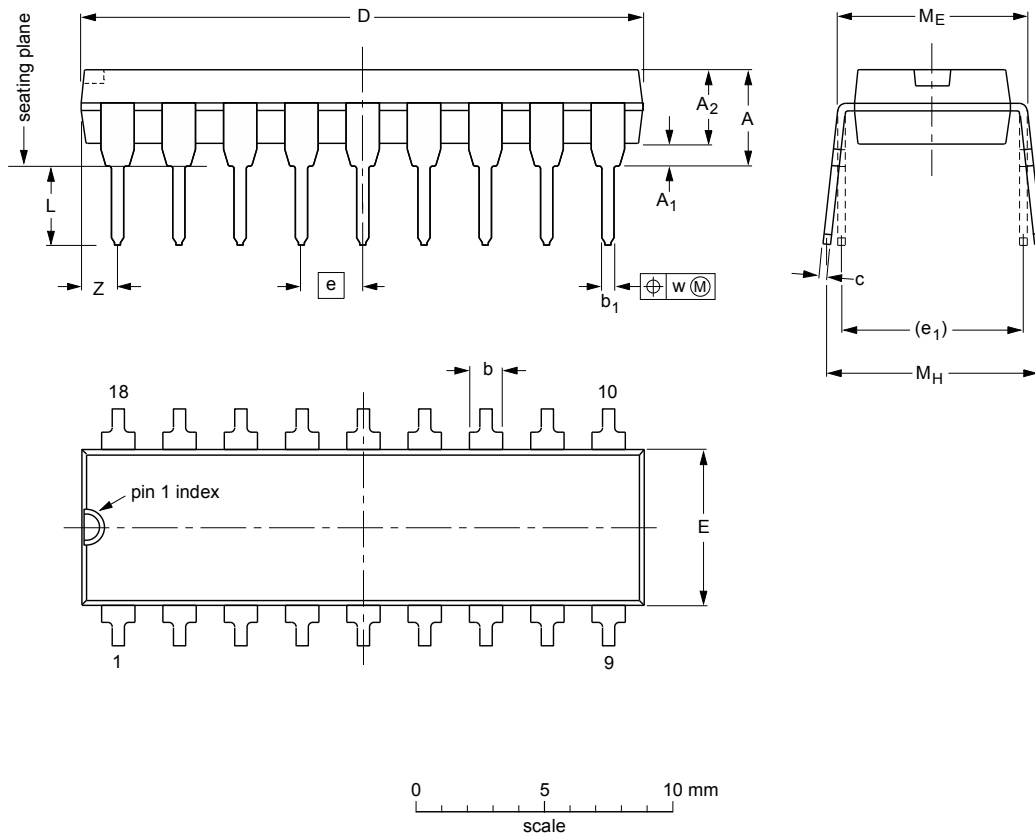
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	22.61	-	22.99	23.37	mm
E	package width	6.22	-	6.35	6.48	mm
A	seated height	[tbd]	-	[tbd]	4.06	mm
A ₂	package height	[tbd]	-	[tbd]	3.38	mm
e	nominal pitch	-	-	2.54	-	mm
n ₂	actual quantity of termination	-	-	18	-	



2. Package outline

DIP18: plastic dual in-line package; 18 leads (300 mil); long body

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DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.06	0.51	3.38	1.63 1.14	0.56 0.43	0.36 0.25	23.37 22.61	6.48 6.22	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	1.65
inches	0.16	0.02	0.14	0.064 0.045	0.022 0.017	0.014 0.010	0.92 0.89	0.255 0.245	0.1	0.3	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.065

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT102-4		MS-001				99-12-27- 03-03-12

Fig. 1. Package outline DIP18 (SOT102-4)

3. Legal information

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